



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Attorney Docket No.: ROH-034

Kazutaka SHIBATA

Application No.: 09/814,057

Examiner: K. Rose

Filed: June 11, 2001

Art Unit: 2822

For: SEMICONDUCTOR DEVICE WITH WARP PREVENTING BOARD
THERE TO (As Amended)

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APR - 2002
TECHNOLOGY CENTER 2800

AMENDMENT UNDER 37 C.F.R. §1.111

Commissioner for Patents
Washington, DC 20231

Sir:

In response to the Office Action dated January 16, 2002, please amend the above-identified application as follows:

IN THE TITLE:

Please change the title of the invention to -- SEMICONDUCTOR DEVICE WITH WARP PREVENTING BOARD JOINED THERETO --.

IN THE CLAIMS:

Please amend claim 1 as set forth below in clean form. Additionally, in accordance with 37 CFR 1.121(c)(1)(ii), amended claim(s) is/are set forth in a marked-up version in the page(s) attached to this Amendment.

1. (Amended) A semiconductor device comprising:
- a semiconductor chip;
 - a wiring board joined to one surface of the semiconductor chip and electrically connected to the semiconductor chip, the wiring board having a wiring board thickness; and
 - a warp preventing board joined to the other surface of the semiconductor chip and composed of the same material as that of the wiring board, the warp

See c17
a